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Substitute for form 1449A/PTO				Complete if Known	
INFORMATION DISCLOSURE STATEMENT BY APPLICANT <i>(use as many sheets as necessary)</i>				Application Number	09/316,580
Sheet	1	of	4	Filing Date	05/21/99
				First Named Inventor	Jack H. Linn
				Group Art Unit	2811
				Examiner Name	Unknown
				Attorney Docket Number	87552.99R134/SE-906D

U.S. PATENT DOCUMENTS					
Examiner Initials ¹	Cite No. ¹	U.S. Patent Document		Name of Patentee or Applicant of Cited Document	Date of Publication of Cited Document MM-DD-YYYY
		Number	Kind Code ² (if known)		
Loke	1	5,102,821		Moslehi	04/07/1992
	2	4,980,306		Shimbo	12/25/1990
	3	5,169,472		Goebel	12/08/1992
	4	5,098,861		Blackstone	03/24/1992
	5	5,387,555		Linn, et al.	02/1995
	6	4,826,787		Muto, et al.	05/1989
	7	2,974,075		Miller	03/1961
	8	3,239,908		Nakamura	03/1966
	9	3,689,357		Jordan	09/1972
	10	4,638,552		Shimbo, et al.	01/1987
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	16	4,878,957		Yamaguchi, et al.	11/1989
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Examiner Initials ¹	Cite No. ¹	Foreign Patent Document		Name of Patentee or Applicant of Cited Document	Date of Publication of Cited Document MM-DD-YYYY
		Office ³	Number ⁴		
Loke	21	JP	2-148821	JP	06/1990
	22	JP	02-206118	JP	1990
	23	JP	62-2122-148	JP	06/1987
	24	EP	0 238 066	EP	09/1987
	25	EP	0 256 397	EP	02/1998
↓	26	EP	0 441 270 A3	EP	08/1991
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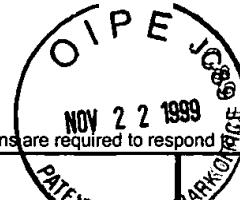
Examiner Signature	Loke	Date Considered	7/23/02
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¹ Unique citation designation number. ² See attached Kinds of U.S. Patent Documents. ³ Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3). ⁴ For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. ⁵ Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST. 16 if possible. ⁶ Applicant is to place a check mark here if English language Translation is attached.

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**INFORMATION DISCLOSURE
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Sheet

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Application Number

09/316,580

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First Named Inventor

Jack H. Linn

Group Art Unit

2811

Examiner Name

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Attorney Docket Number

87552.99R134/SE-906D

OTHER PRIOR ART -- NON PATENT LITERATURE DOCUMENTS

Examiner Initials*	Cite No. ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
Loke	28	M. Shimbo, et al., "Silicon-to-Silicon Direct Bonding Method", <u>Journal of Applied Physics</u> , Vol. 60(8), pp. 2987-2989, (October 1986).	
	29	Wolf, et al., "Silicon Processing for the VLSI Era", <u>Lattice Press</u> , Vol 1., pp. 390-391, 1986.	
	30	Sorab K. Ghandi, "Silicides", <u>VLSI Fabrication Principles</u> , John Wiley & Sons, pp. 435-437, 1983.	
	31	S.P. Murarka, "Refractory Silicides For Integrated Circuits", <u>J. Vac. Science Technology</u> , Vol. 17(4), pp. 775-792, (July/August 1980).	
	32	Toshiba KK, "Bonding Method for Semiconductor Wafer", <u>Patent Abstracts</u> , Vol. 9, No. 227 E-355, A 60121715, June 11, 1985, Japan.	
	33	Fukuroda, et al., "Si Wafer Bonding with Ta Silicide Formation", <u>Japanese Journal of Applied Physics</u> , Vol. 30, No. 10A, pp. 1693-1695, (October 1, 1991), Tokyo, Japan.	
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	36	Imthurn et al., "Bonded Silicon-On-Sapphire Wafers and Devices", <u>Journal of Applied Physics</u> , Vol. 72, No. 6, pp. 2526-2527, (September 15, 1992), New York.	
	37	Godbey, et al., "Fabrication of Bond and Etch-Back Silicon On Insulator Using Strained Si. sub 0.7 Ge, sub 0.3 Layer as An Eth Stop", <u>Journal of Electrochemical Society</u> , Vol. 137, No. 10, pp. 3219-3223, (October 1990), New Hampshire.	
↓ Loke	38	J. Lasky, et al., "Silicon-On Insulator (SOI) By Bonding and Etch-Back", <u>1985 IEDM Tech., Dig.</u> , Vol. 85, pp. 684-687.	

Examiner
Signature

Loke

Date
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